DECLARATION AND POWER OF ATTORNEY FOR PATENT APPLICATION

As a below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name;

I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled

Title:	SUBSTRATE ON CHIP (SOC) MULTIPLE-CHIP MODULE (MCM) WITH CHIP-SIZ	ZE-
	PACKAGE (CSP) READY CONFIGURATION	

	the specification of which (che	eck one)	
	\underline{X} is attached hereto.	,	
	was-filed on	as Application Serial No	and was amended on
The State of	I hereby state that I have revieus including the claims, as amend	iewed and understand the cont led by any amendment referred	tents of the above-identified specification, to above.
	I acknowledge the duty to application in accordance with	disclose information which h Title 37, Code of Federal Reg	is material to the examination of this ulations, §1.56(a).
	application(s) for patent or in	nventor's certificate listed bel ent or inventor's certificate h	Jnited States Code §119 of any foreign ow and have also identified below any aving a filing date before that of the
1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1	Prior Foreign Application(s)		Priority ClaimedYes _ No
į.Ł	(Number) (Co	ountry) (Day/Month	h/Year Filed)
il.	I hereby claim the benefit und	ler Title 35, United States Code	, §120 of any United States application(s)
42	listed below and, insofar as the	e subject matter of each of the	claims of this application is not disclosed
	In the prior United States ap	plication in the manner prov	ided by the first paragraph of Title 35,
	37 Code of Federal Regulation	knowledge the duty to disclose	e material information as defined in Title
	application and the national or	or PCT international filing date	d between the filing date of the prior
	60/087,604	June 1, 1998	Pending
	(Application Serial No.)		(Status) (patented, pending, abandoned)
		ents made herein of my own k	nowledge are true and that all statements
	made on information and belie	ef are believed to be true; and	further that these statements were made
	with the knowledge that will	Iful false statements and the	like so made are punishable by fine or
	imprisonment, or both, under	Section 1001 of Title 18 of the	United States Code and that such willful
	false statements may jeopardize	e the validity of the application	or any patent issued thereon.
	POWER OF ATTORNEY: As	a named inventor, I hereby a	ppoint the following attorney(s) and/or
	connected therewith. (list name	e and registration number)	less in the Patent and Trademark Office
•		Bo-In Lin(#33,948)	

Direct Telephone Calls to: (name and telephone number)Bo-In Lin, (650) 949-0418 (Tel) 949-4118(Fax)



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page 2 of 2

Docket No. PTLIN-9801

Full name of sole or first inventor: Paul T. Lin				
Inventor's signal	ure: Part Tan	Date: 5/18/99		
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Citizenship:	United States of America			
Post office addres	s: 673 Hillcrest Terrace Fremont, California 94539	t Min 466 van was vier van een van dan very pen 40 Min 1966 pal apin July aan alee		
Full name of sec	ond joint-inventor:			
Inventor's signat		Date:		
Residence:				
Citizenship:				
Post office addres				
Full name of this	rd joint-inventor:			
Inventor's signat		Date:		
Residence:				
Citizenship:				
Post office address				
Full name of four				
nventor's signatu	ire:	Date:		
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Author: BolnLin (BolnLin@aol.com> at Internet

Date: 5/21/98 4:34 PM

Priority: Normal TO: Paul T. Lin

Subject: Small Entity Form

- Message Contents -

In the United States Patent and Trademark Office

Pirst/Sole Applicant: Paul T. Lin

Docket No. PTLIN-9801

Title: SUBSTRATE ON CHIP (SOC) MULTIPLE-CHIP MODULE (MCM) WITH

CHIP-SIZE-PACKAGE (CSP) READY CONFIGURATION

Small Entity Declaration - INDEPENDENT INVENTOR(3)

I hereby declare that I am an independent inventor as defined in Section 1.9(c) of 37 CFR. I have not assigned, granted, conveyed or licensed, and am under no obligation under contract or law to assign, grant, convey, or license any rights in the invention to any person who could not likewise be classified as an independent inventor if that person had made the invention, or to any concern which would not qualify as small business concern or a nonprofit organization.

Signature of the First/(Sole) Inventor

Date

May 21, 1998